

Multiscale Modelling of Dielectric Breakdown in Amorphous HfO₂

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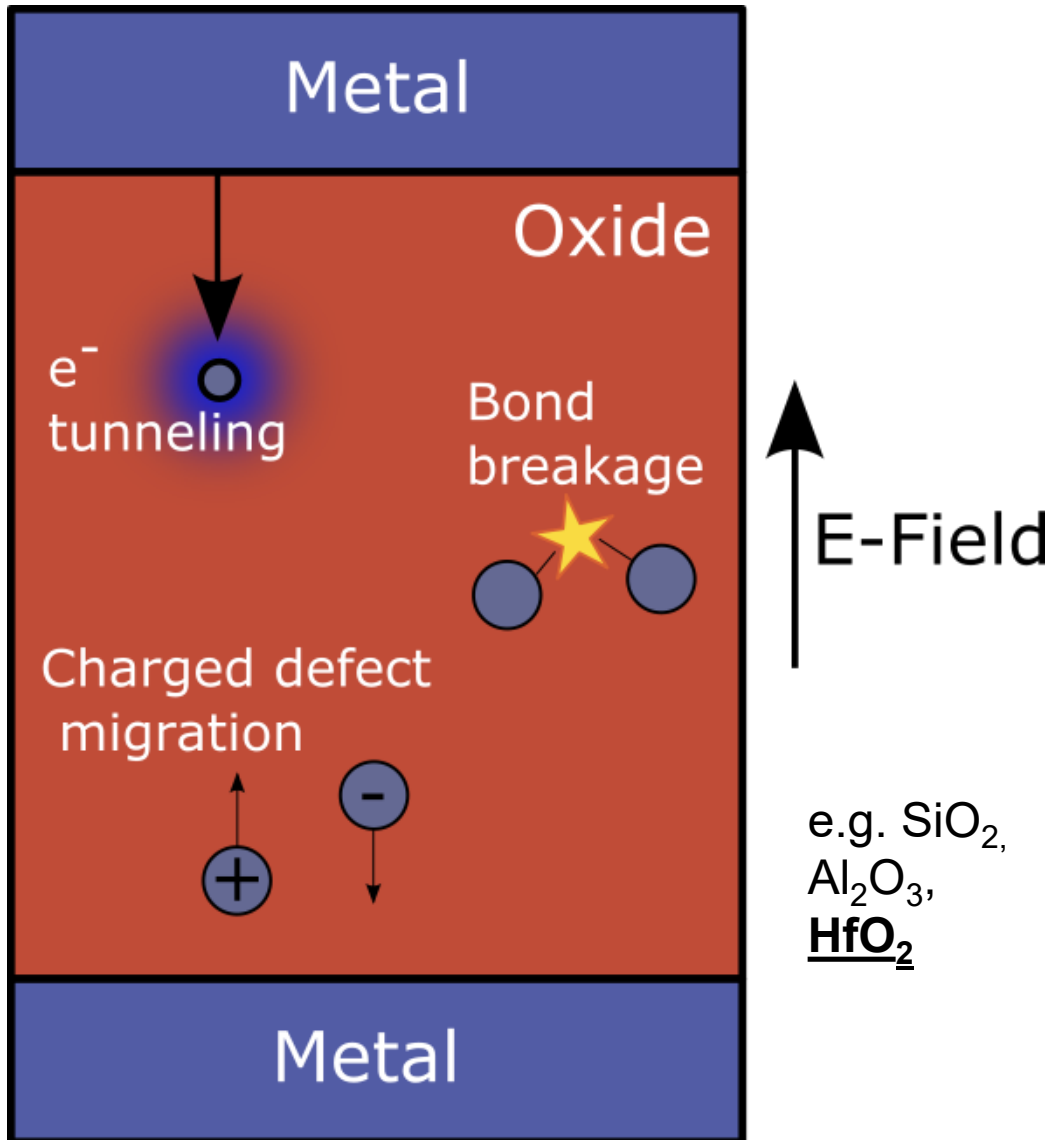
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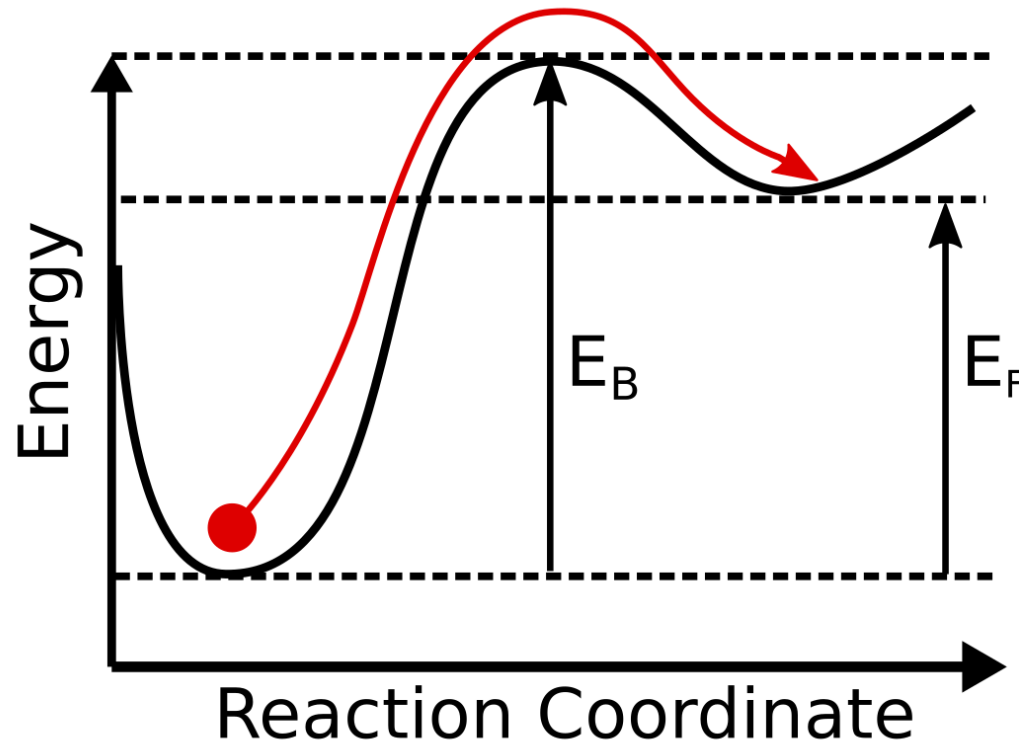
Engineering and Physical Sciences
Research Council





- The Metal-Oxide-Metal or (SC) stack is common to many nanoelectronic devices
- Application of E-Field leads to three phenomena (in bulk):
 1. **Charging** due to tunneling into defects
 2. Defect generation (**Oxide degradation**)
 - Related to charging (process 1)
 - Breakdown related to O Vacancy generation
 3. Migration of charged species/defects
 - Charged interstitial and vacancy defects drift under E-Field Effect

- For “things to happen” (defect migration, defect generation) we must overcome an energetic barrier (i.e. Activation energy):



E_F = Formation Energy
 E_B = Energy Barrier

Reaction Coordinate

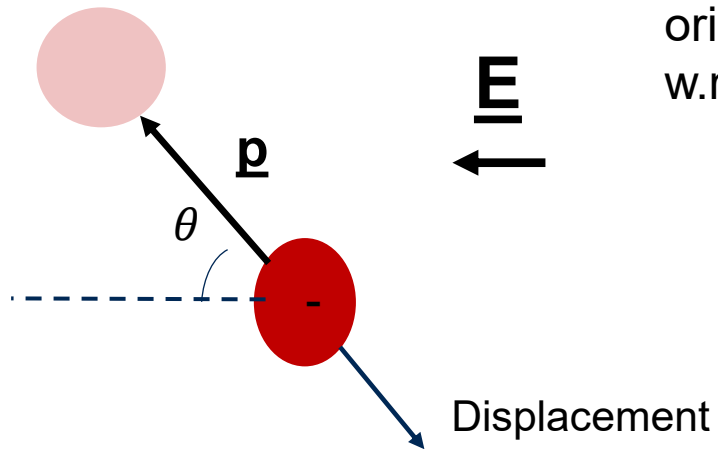
Schematic of a general pathway

- Formation energy can be positive or negative
- Can **E**-field accelerate processes by reducing the energy barrier?

E-field can affect barrier heights in two ways:

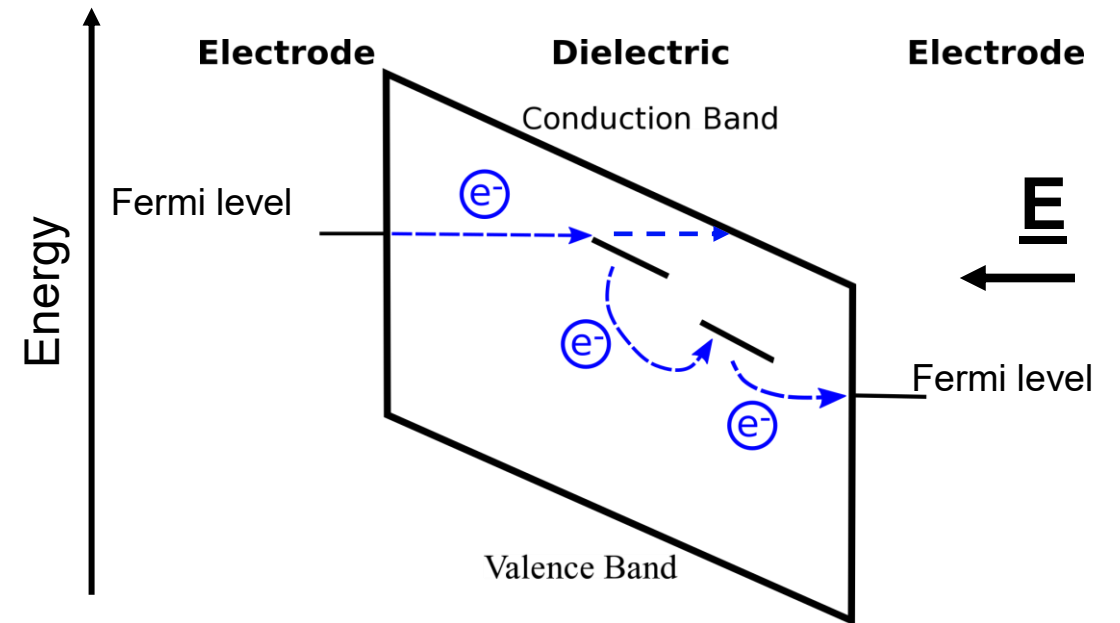
1- “Direct” Effect: Displacement of oxygen ion creates dipole which interacts with **E** field.

$$U = -\mathbf{E} \cdot \mathbf{p}$$



Effect depends on orientation of **E** field w.r.t. dipole

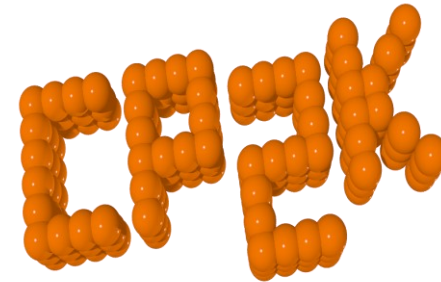
2- Electron Injection: **E** field can realign relative energy of electrode Fermi level and trap states



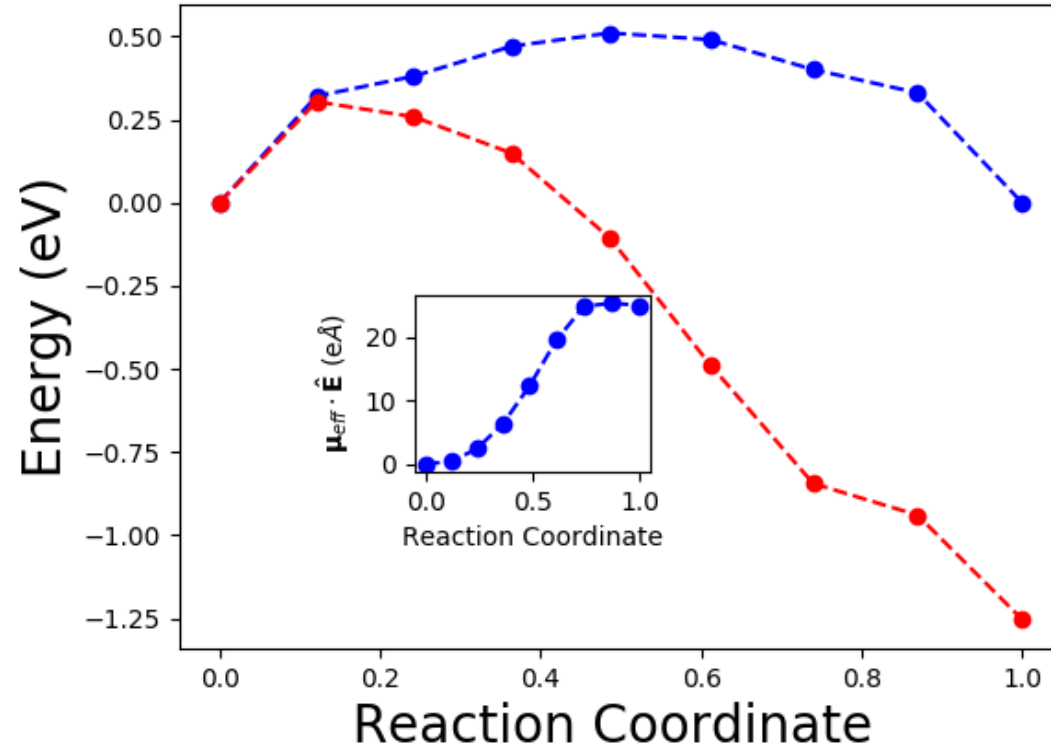
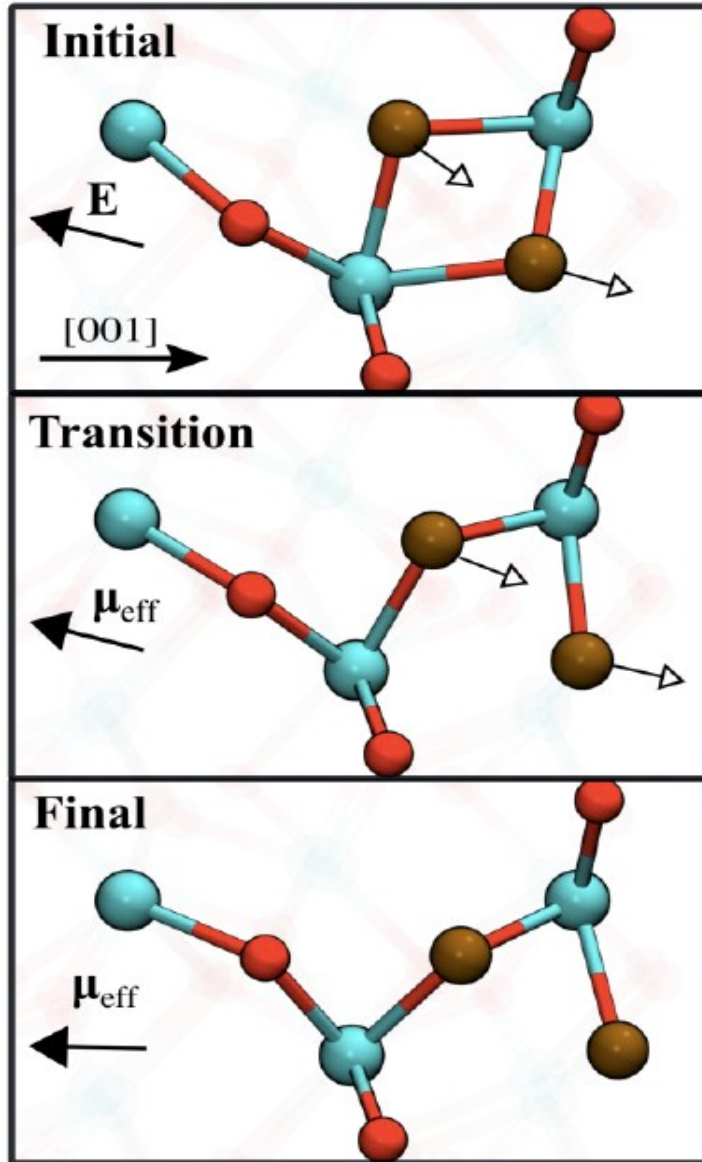
Charging leads to ‘bond weakening’

- Calculation of defects and defect processes use density functional theory (DFT)

- Software: CP2K



- XC Functional: PBE0-TC-LRC. This is a variant of the hybrid PBE0 functional.
 - Hybrid functionals contain non-local exchange, which improves accuracy of localized states associated with defects.
- Electric field interaction with charged particles calculated using the modern theory of polarization. ("Berry phase approach", see Resta, Raffaele et al *Physics of Ferroelectrics*. 2007. 31-68.)



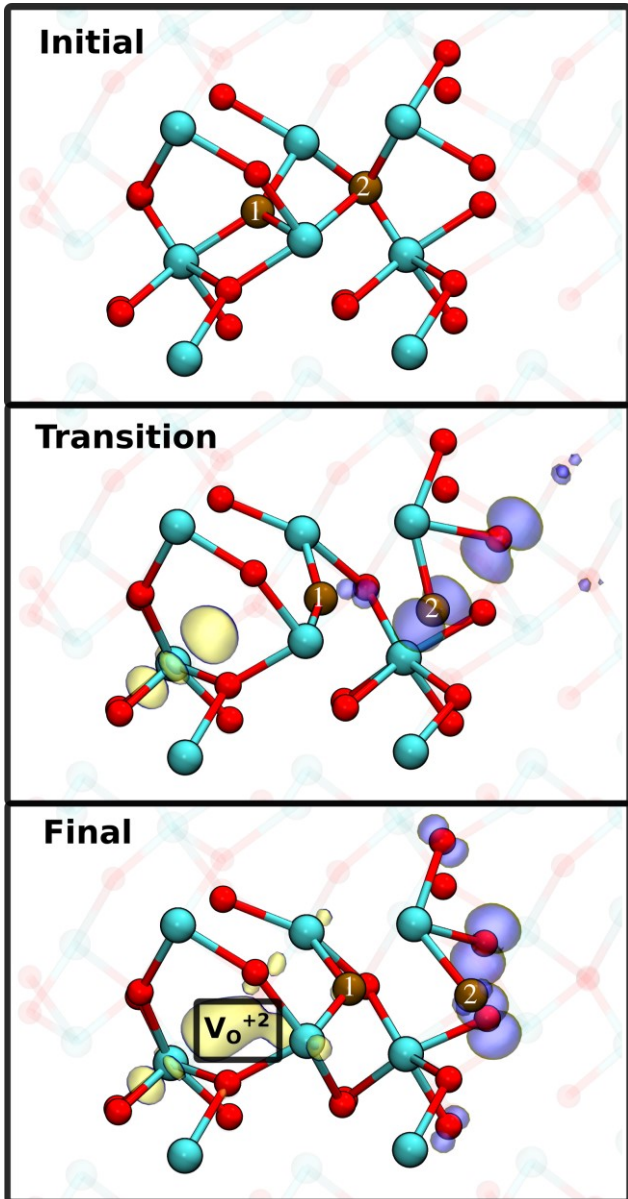
Blue Line = Zero applied field

Red Line = 0.5 Vnm⁻¹ applied field

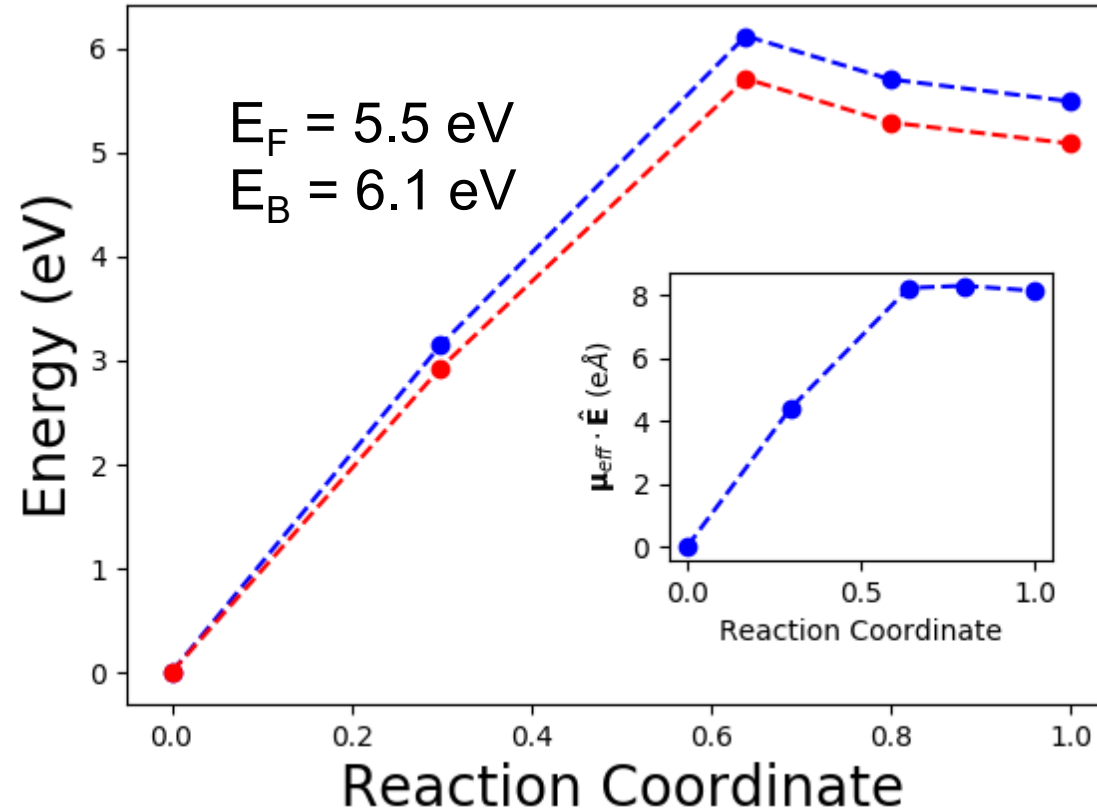
- O_I^{-2} defect moves by interstitialcy mechanism
- Field free barrier is only 0.5 eV
- E-Field reduction leads to 0.25 eV barrier height at 0.5 Vnm⁻¹

O Vacancy Generation

Reaction pathway:



Perfect Crystal $\rightarrow V_O^{+2} + O_I^{-2}$



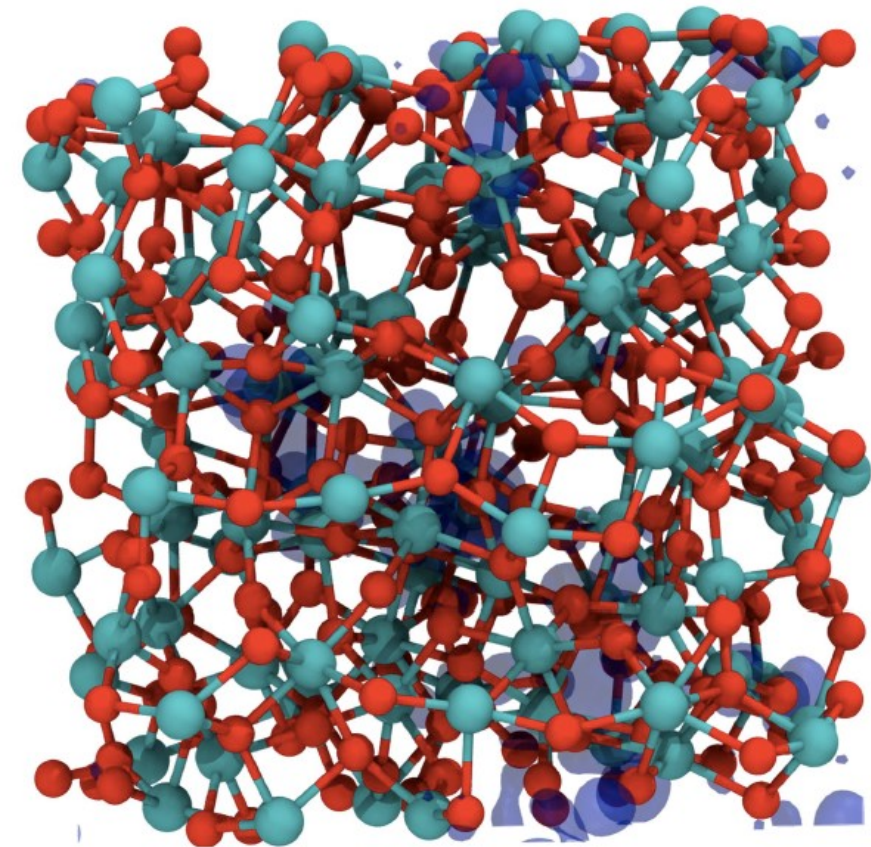
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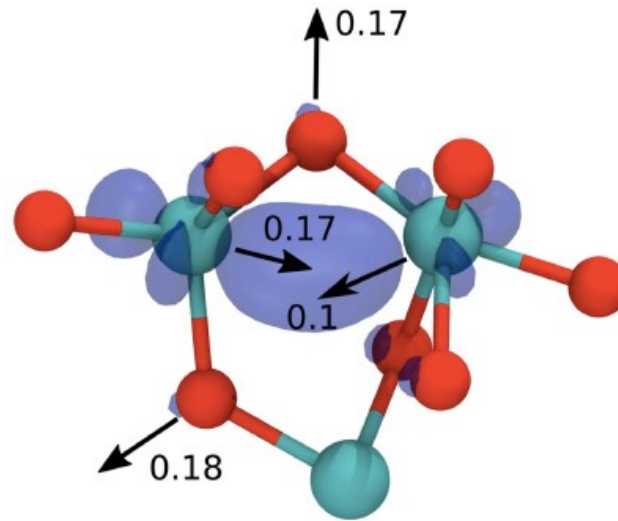
- Barrier height reduction is very small relative to activation energy
- 5 eV activation energy far too high for room T effects
- Direct effect of \mathbf{E} -field not strong enough to induce vacancy production.

Previous work shows that crystal and amorphous HfO_2 can self-trap electrons.

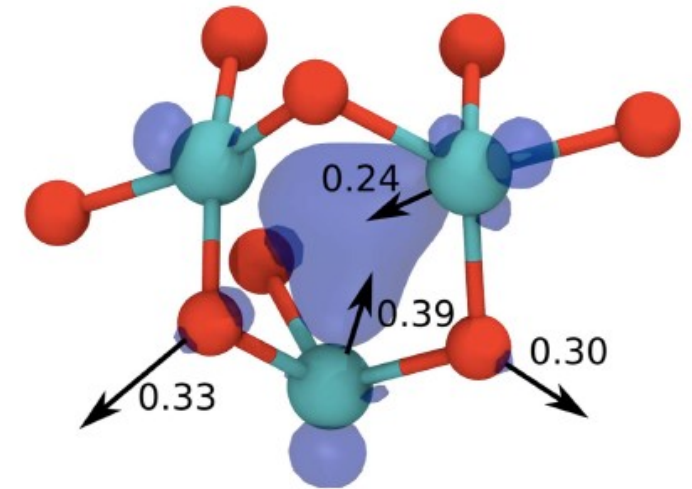
Intrinsic Deep Trap states exist in amorphous HfO_2 due to disorder!



Part-localized state in a- HfO_2



e⁻ trap in HfO_2

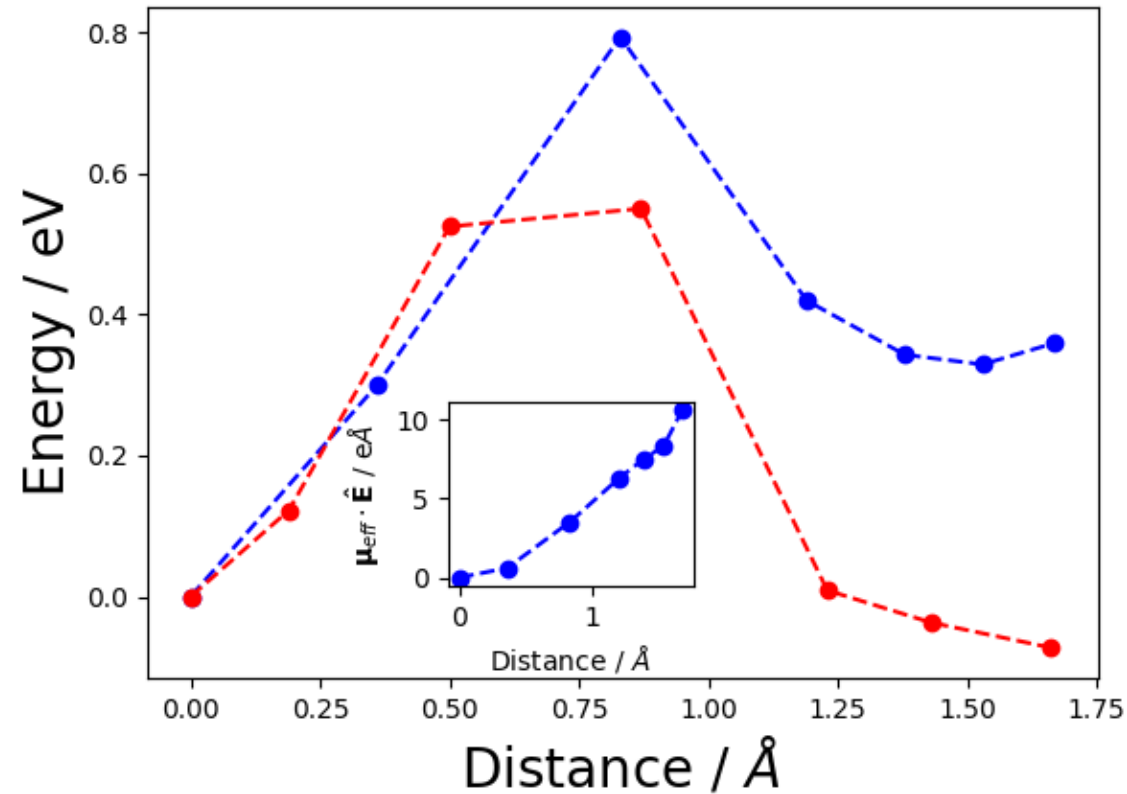
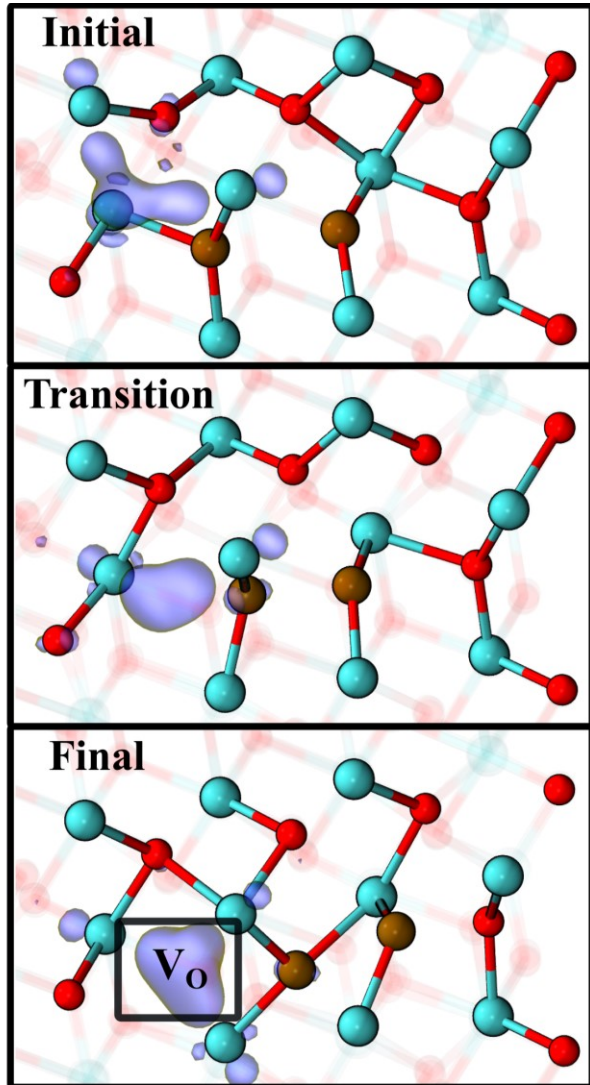
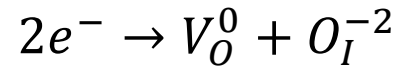


Double e⁻ trap in HfO_2

- Strand, Jack, et al. "Intrinsic electron trapping in amorphous oxide." *Nanotechnology* 29.12 (2018): 125703.
- Strand, Jack, et al. "Intrinsic charge trapping in amorphous oxide films: status and challenges." *Journal of Physics: Condensed Matter* 30.23 (2018): 233001.

Vacancy Generation from e⁻ Trap

Start from 2e⁻ trap:

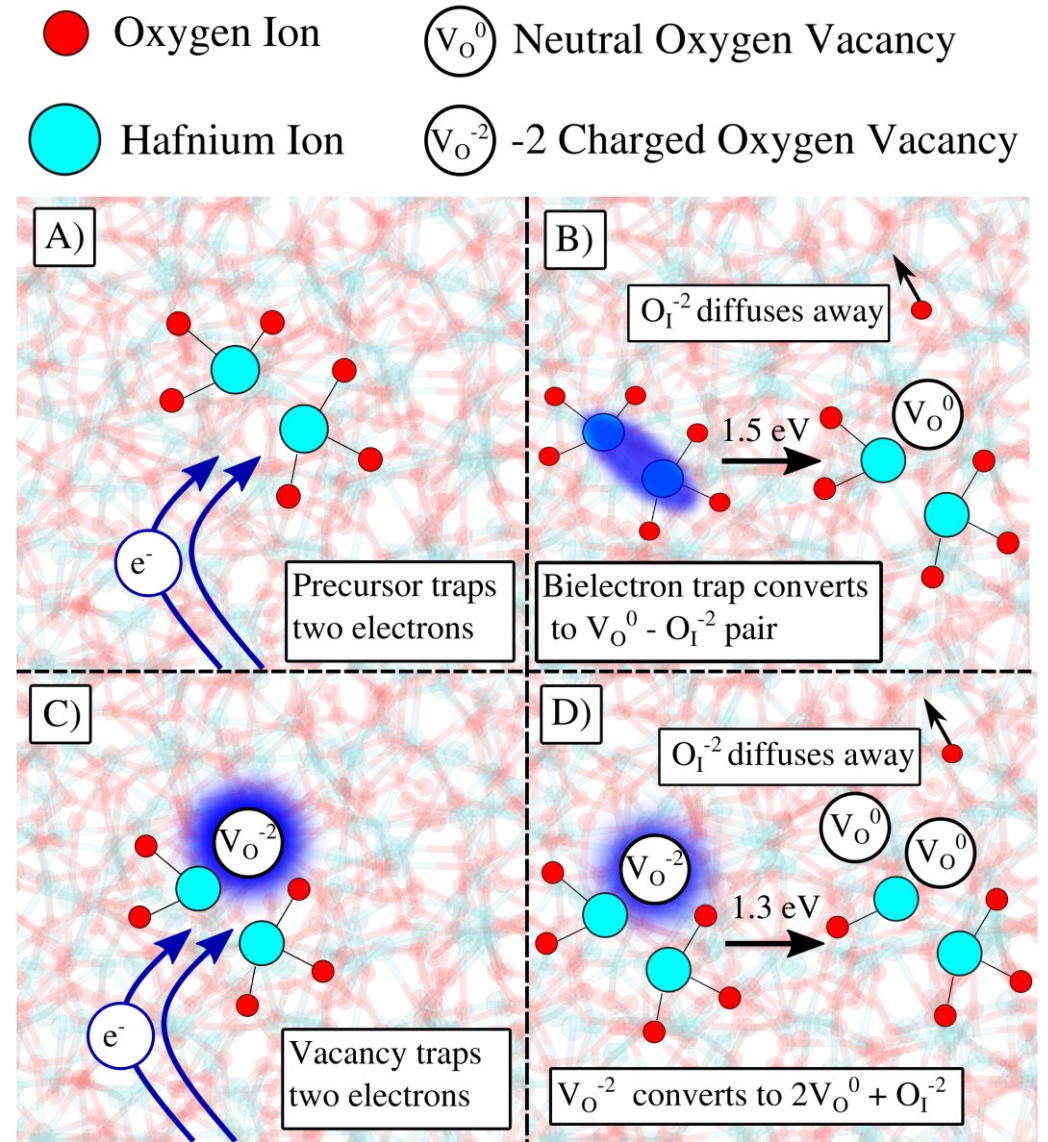


Blue Line = Zero applied field (e-trap effect only)

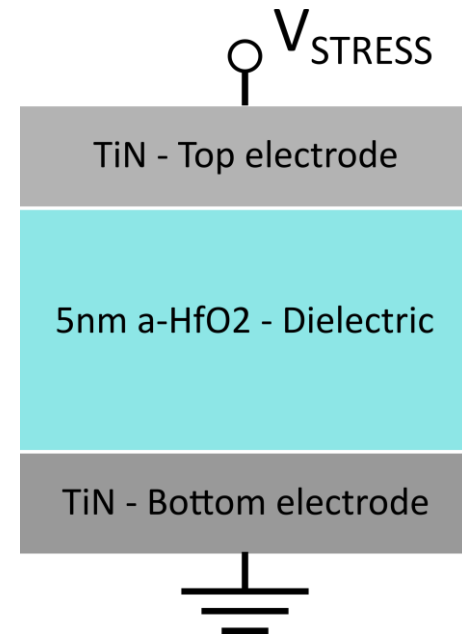
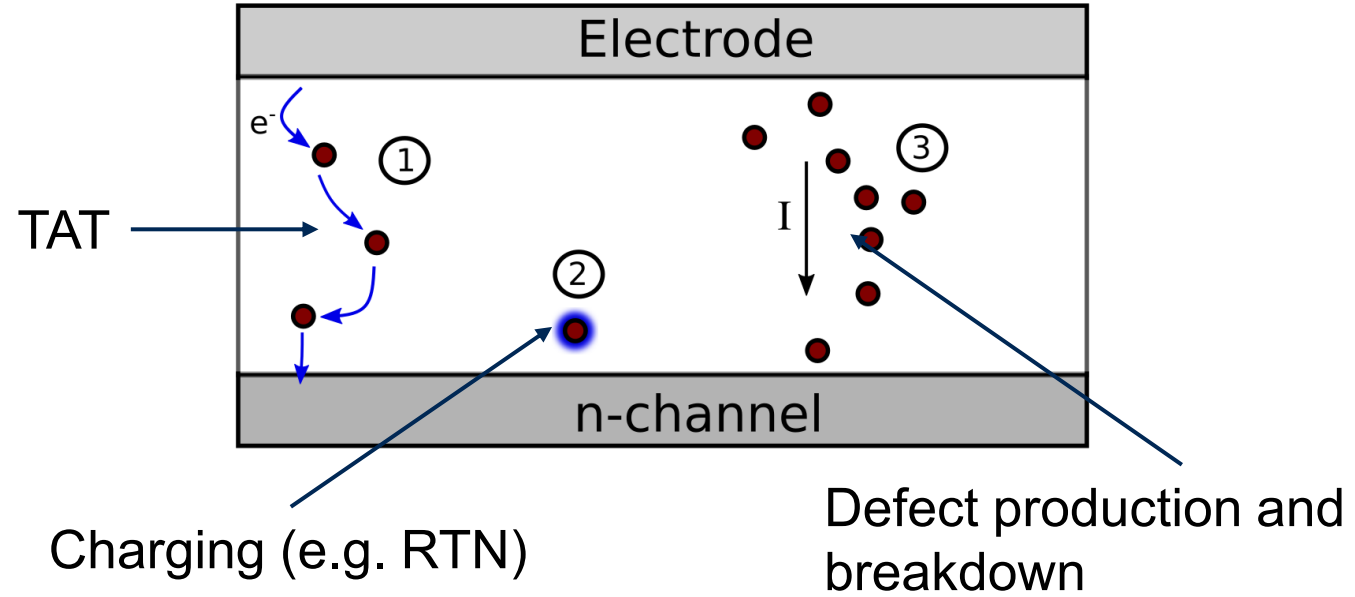
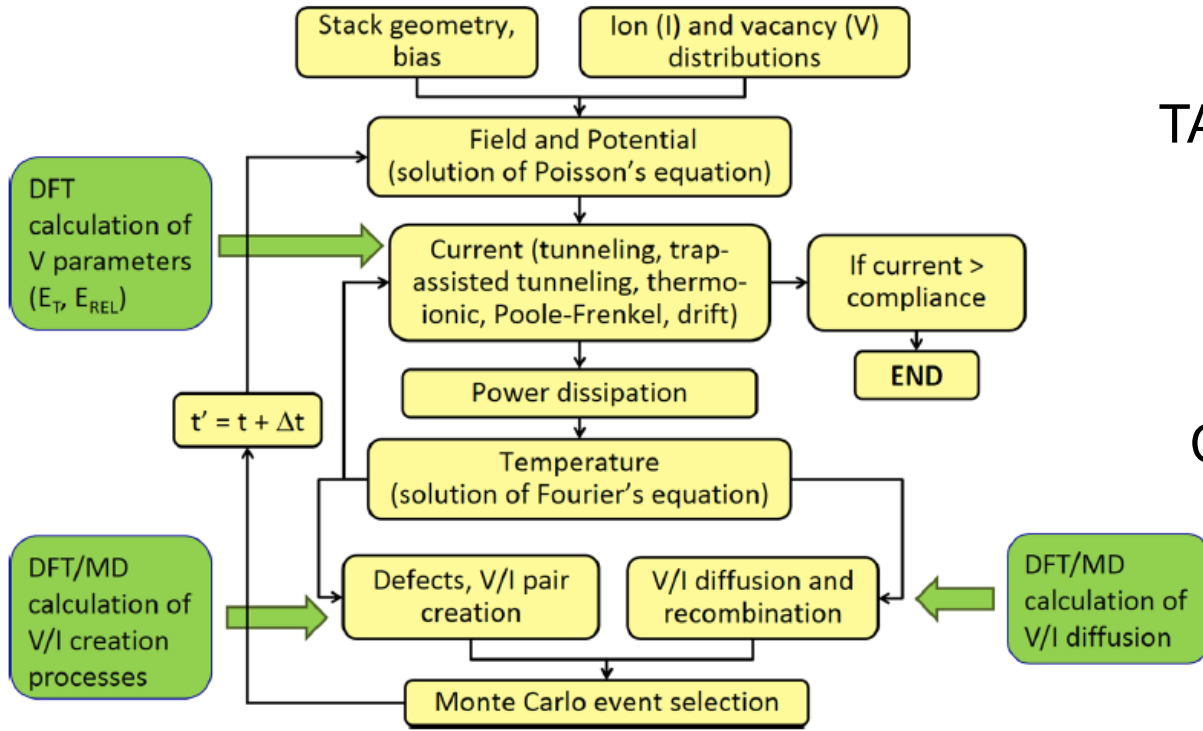
Red Line = 0.5 Vnm⁻¹ applied field (e-trap effect + $-E \cdot p$ effect)

- Defect generation near 2- charged trap has barrier height of 0.8 eV.
- Electron injection effect leads to 5 eV barrier height reduction!
- Direct effect of E-Field responsible for further ~0.5 eV reduction.

- Trapping of electrons can generate oxygen vacancies
- Oxygen Vacancies can also trap electrons, and generate more vacancies by the same mechanism
- These reactions combined provide a mechanism for degradation of the oxide under electrical field stress

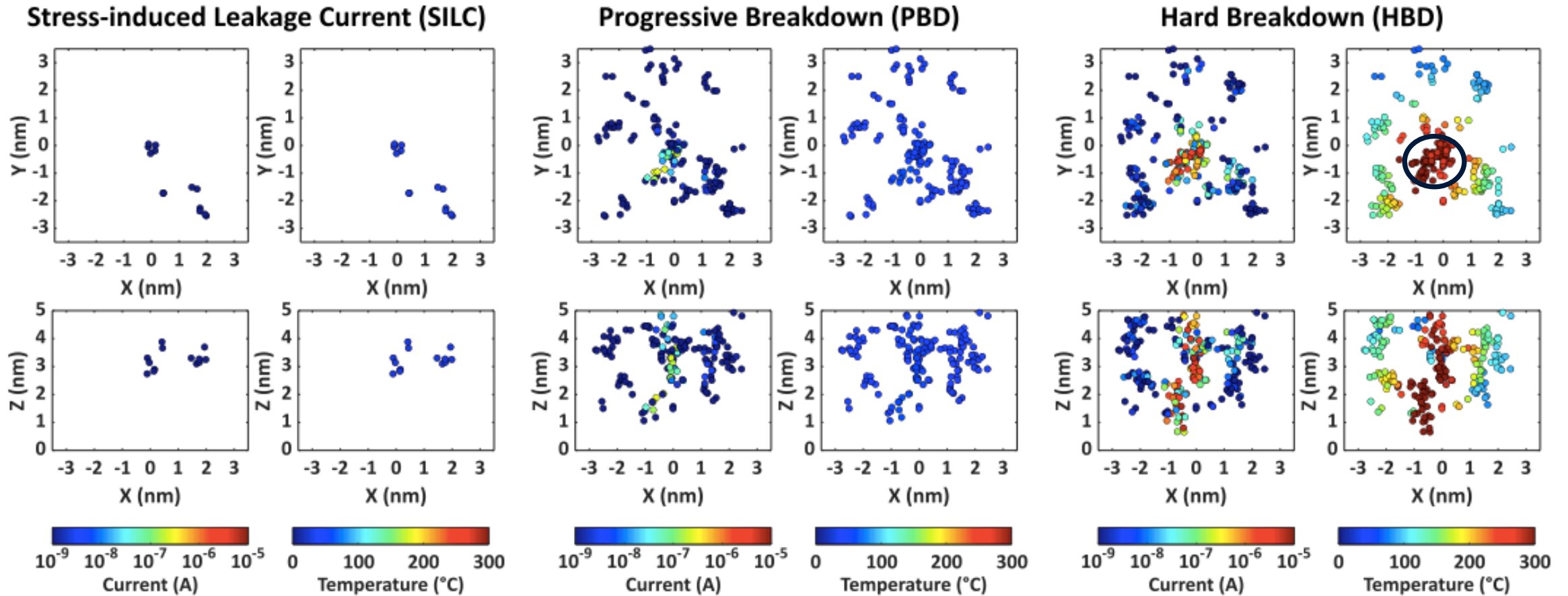


Ginestra™ :



- Simulated device has area of 7nm x 7nm
- Initial vacancy calculation $\sim 1 \times 10^{19} \text{ cm}^{-3}$
- Statistical sample of 20 devices

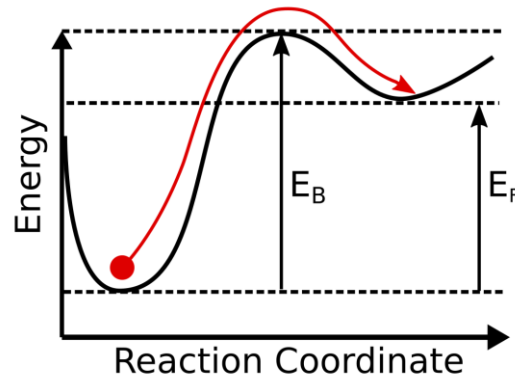
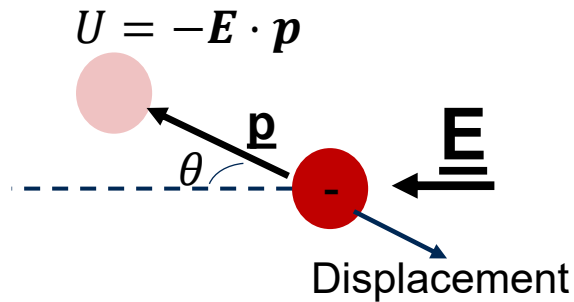
- Formation energy, barrier heights et cetera can parameterize multiscale models
- Simulate defect generation and TAT current in a MIM device



- Up until hard breakdown, defects are generated relatively uniformly
- At hard breakdown, a hot spot develops where the temperature and the number of defects is very large.

Field-Dipole Interaction

Charge defect reaction have typical barrier reduction of ~ 0.5 to 1 eV

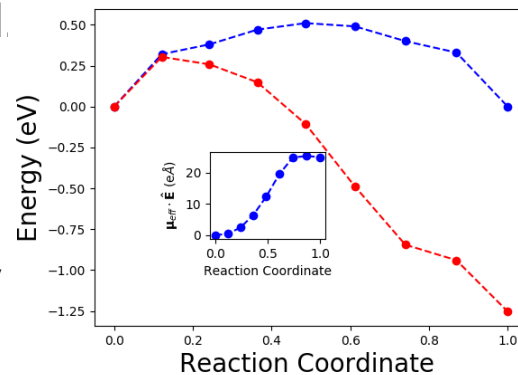


Migration of Charged Defects

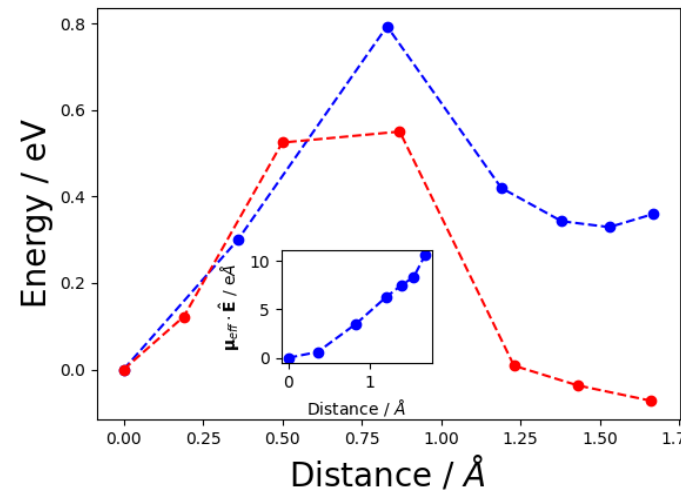
Migration of charged defects can be rapidly accelerated using an E-Field.

- Only affected by Field-Dipole interaction

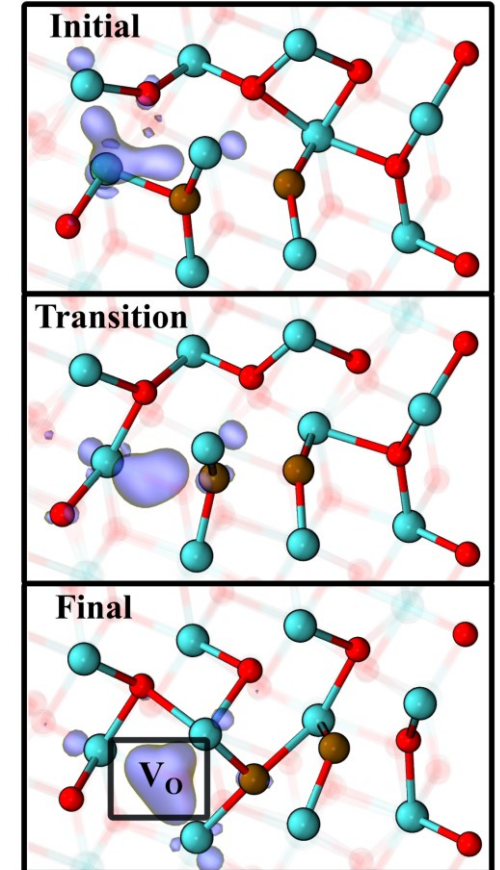
→ Barrier reduction ~ 0.5 eV



Electron Injection into localized states



(B) [001] Direction



Injection of carriers into trap states can reduce defect generation barrier heights by ~ 5 eV.

Defect production leads to oxide degradation.

Acknowledgments:

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- Dr. Moloud Kaviani
- Dr. Andrea Padovani
- Dr. Paolo La Torraca



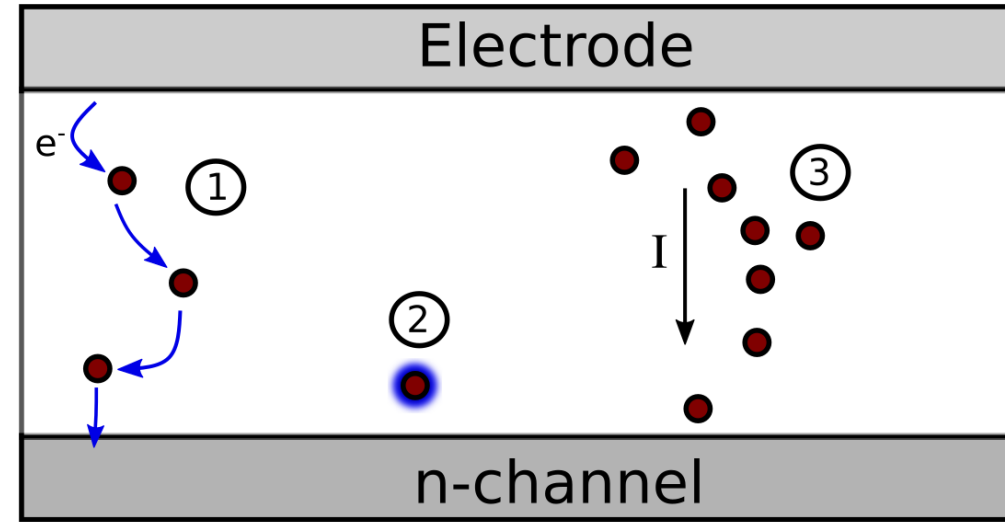
Relevant Publications

- Strand, Jack, et al. "Dielectric breakdown in HfO₂ dielectrics: Using multiscale modeling to identify the critical physical processes involved in oxide degradation." *Journal of Applied Physics* 131.23 (2022): 234501.
- Strand, Jack W., et al. "Effect of electric field on defect generation and migration in HfO₂." *Physical Review B* 102.1 (2020): 014106.
- Padovani, A., et al. "A microscopic mechanism of dielectric breakdown in SiO₂ films: An insight from multi-scale modeling." *Journal of Applied physics* 121.15 (2017): 155101.
- Gao, David Z., Al-Moatasem El-Sayed, and Alexander L. Shluger. "A mechanism for Frenkel defect creation in amorphous SiO₂ facilitated by electron injection." *Nanotechnology* 27.50 (2016): 505207.

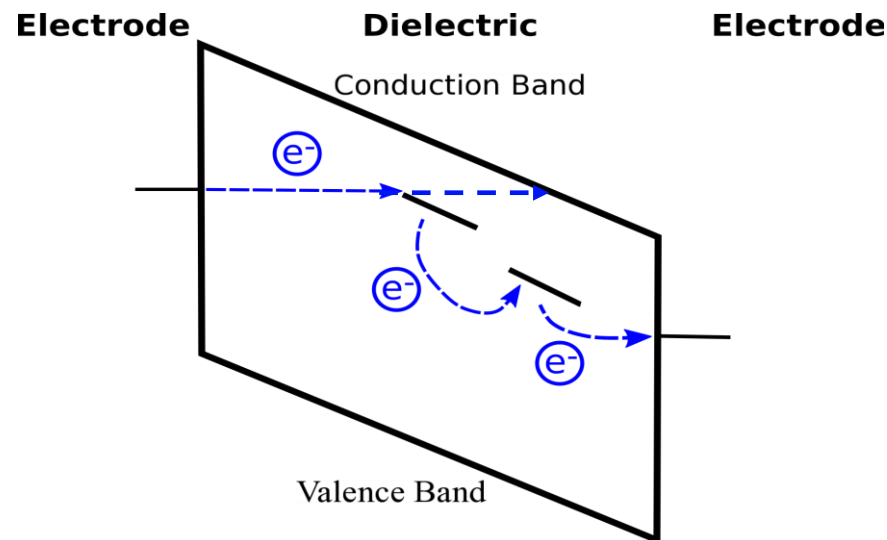
Extra Slides...

Charging, bond breakage and migration lead to three main consequences:

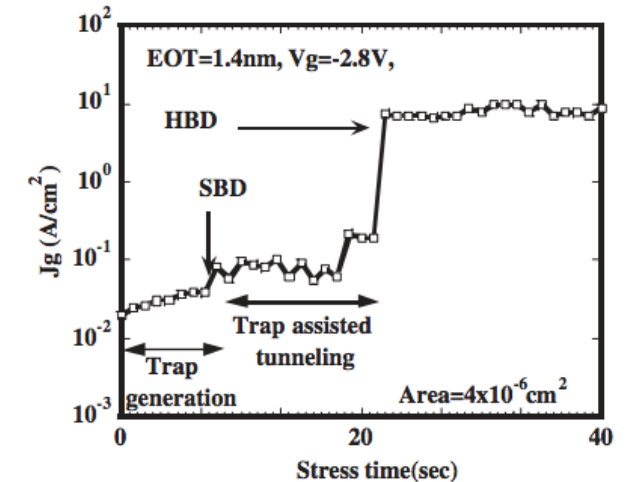
1. Trap Assisted Tunneling (SILC)
2. Charging and de-charging of defects (RTN, threshold voltage shift)
3. Buildup of defect population and current (dielectric breakdown)



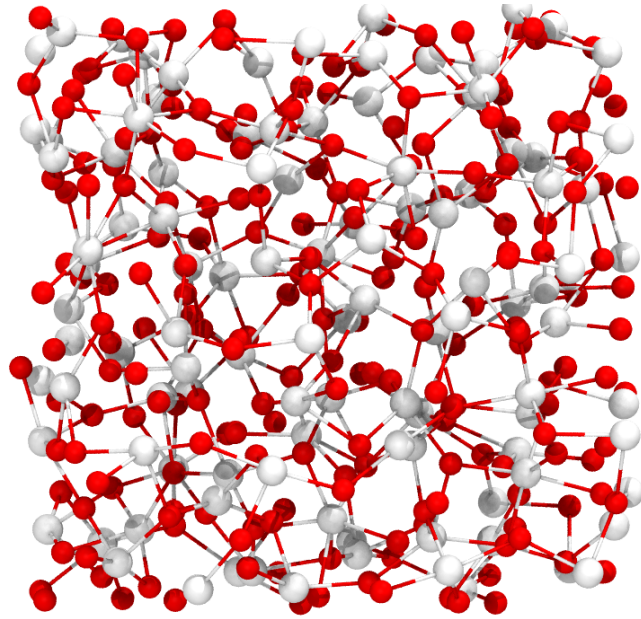
Trap Assisted Tunneling



Dielectric Breakdown



Kim et al Microelectronics Reliability 44(2) 2004



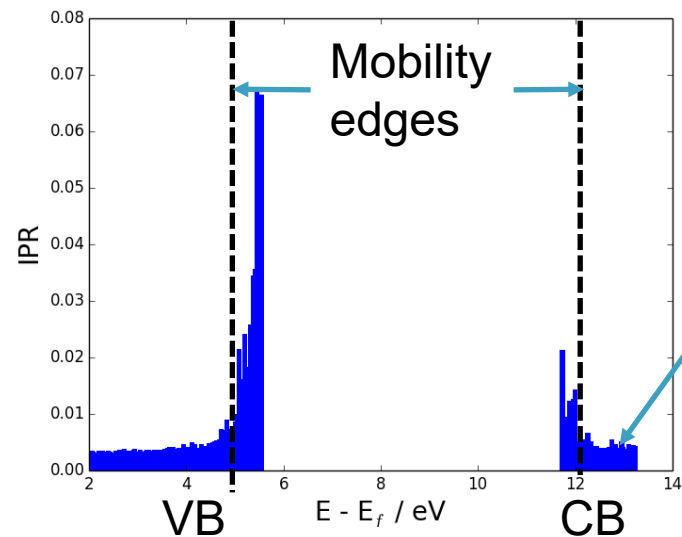
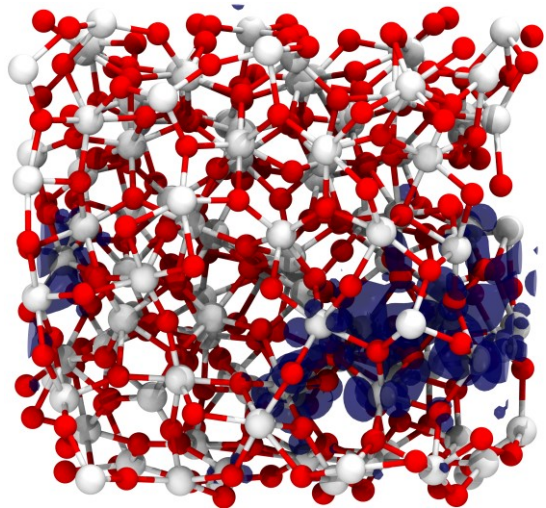
Geometric Structure:

Type	CN	96	324	768	1500	6144
	5	8.1[11.6]	9.6[14.1]	9.0	9.7	8.2
Hf	6	47.6[48.7]	65.6[60.9]	78.1	75.5	75.3
	7	44.3[39.7]	24.8[25.0]	12.9	14.8	16.5
O	2	6.4[10.5]	6.0[10.9]	6.1	6.6	5.8
	3	69.2[65.0]	83.1[71.0]	85.9	84.3	84.2
	4	24.4[24.5]	10.9[18.1]	8.0	9.1	10.0

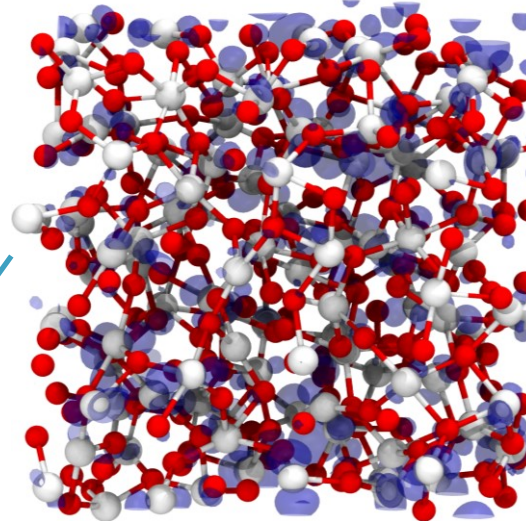
- Average density = 9.6 g cm⁻³
- Undercoordinated Hf ions
- Extended bond lengths

Electronic Structure:

CBM State



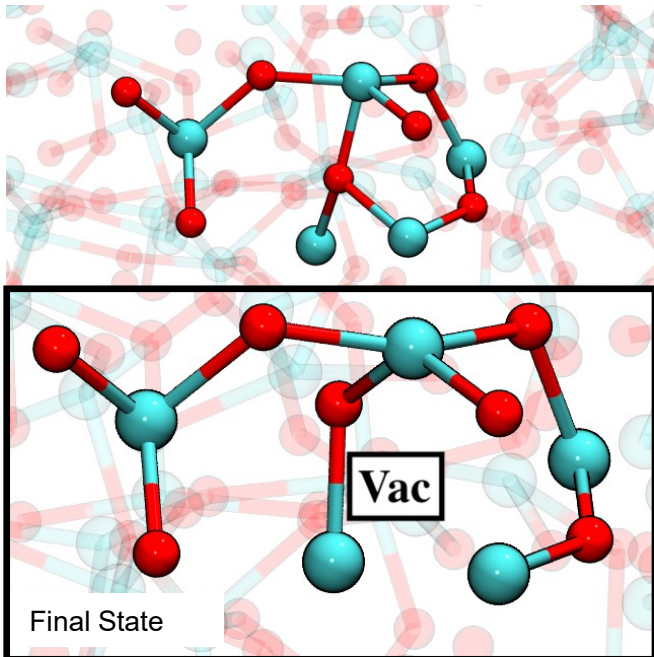
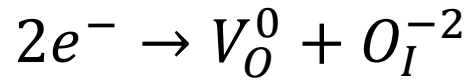
Deep CB state



$$\text{IPR}(\psi_n) = \frac{\sum_i^N c_{ni}^4}{(\sum_i^N c_{ni}^2)^2}$$

Large IPR = localized state
Small IPR = Delocalised state

Same reaction mechanism to crystal:



Spread of activation energy heights: 1.1 to 3 eV

Multiscale modelling using Ginestra™ show how trap-based model explains degradation:

